

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A sugar wafer batter comprising:

(i) a grain component comprising wheat flour and ~~uncooked~~ cereal grits in an amount sufficient to be baked into a crisp wafer; a sugar additive comprising sucrose, a reducing sugar, or a mixture thereof in an amount sufficient to provide a sweet taste to the wafer; and water in an amount sufficient to form a batter; or

(ii) a grain component comprising wheat flour in an amount sufficient to be baked into a crisp wafer; a sugar additive comprising sucrose and a reducing sugar in an amount sufficient to provide a sweet taste to the wafer; and water in an amount sufficient to form a batter;

wherein a sugar wafer obtained by baking batter (i) or (ii) is sufficiently flexible under ambient conditions for ~~more than 40 seconds to~~ at least 70 ~~about 100 seconds~~ after baking to enable further processing of the wafer.

2. (Original) The sugar wafer batter of claim 1, wherein the grain component contains cereal grits and the ratio of wheat flour to cereal grits is from 10:90 to 80:20.

3. (Original) The sugar wafer batter of claim 2, wherein cereal grits are corn grits, maize grits, wheat grits, oat grits, rice grits, or a combination thereof.

4. (Original) The sugar wafer batter of claim 1, wherein the water is present in an amount of from 100 to 160 parts by weight per 100 parts by weight of the grain component.

5. (Original) The sugar wafer batter of claim 1, wherein the sugar additive is present in an amount of from 50 to 100 parts by weight per 100 parts by weight of the grain component.

6. (Original) The sugar wafer batter of claim 1, wherein the sugar additive contains a reducing sugar and the reducing sugar is fructose, glucose, glucose syrup, dextrose, corn syrup, invert sugar, a fruit juice containing a reducing sugars, honey, or a mixture thereof.

7. (Currently Amended) The sugar wafer batter of claim 1, wherein the sugar wafer is sufficiently flexible for more than 50 seconds to 100 seconds after baking to enable further processing.

8. (Original) A process for preparing a sugar wafer comprising baking the sugar wafer batter of claim 1 for 0.5 to 2 minutes at a temperature of from 140°C to 180°C to form a sugar wafer.

9. (Currently Amended) A baked sugar wafer comprising fat, wheat flour, ^{allow} cereal grits, sucrose, and water, wherein the combination of fat, wheat flour, cereal grits, sucrose, and water account for at least 95 percent by weight of the sugar wafer; the amount of water in the sugar wafer is from about 0.5% to 6% by weight based on the weight of the sugar wafer; the sucrose is present in an amount of from 50 to 100 parts by weight per 100 parts by weight of the wheat flour and cereal grits; and the ratio of wheat flour to cereal grits to is from 10:90 to 80:20; and whereby the sugar wafer is sufficiently flexible under ambient conditions for more than 40 seconds to at least 70 ~~about 100~~ seconds after baking to enable further processing of the wafer.

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10. (Original) The sugar wafer according to claim 9, further comprising one or more of milk, cream, milk powder, whole egg, egg powder, soya flour, salt, lecithin, vanilla crystals, or a raising agent.

11. (Previously Amended) The sugar wafer of claim 10, wherein 20 percent to 80 percent of the sucrose is replaced with a reducing sugar component.

12. (Original) The sugar wafer according to claim 11, further comprising one or more of milk, cream, milk powder, whole egg, egg powder, soya flour, salt, lecithin, vanilla crystals, or a raising agent.

13. (Previously Amended) A baked sugar wafer comprising fat, wheat flour, sucrose, a reducing sugar, and water, wherein the combination of fat, wheat flour, sucrose, a reducing sugar, and water account for at least 95 percent by weight of the sugar wafer; the amount of water in the sugar wafer is from about 0.5% to 6% by weight based on the weight

of the sugar wafer; the sucrose and reducing sugar are present in an amount of from 50 to 100 parts by weight per 100 parts by weight of the wheat flour; and the ratio of sucrose to reducing sugar is from 80:20 to 20:80; and whereby the sugar wafer is sufficiently flexible under ambient conditions for more than 40 seconds to at least 70 ~~about 100~~ seconds after baking to enable further processing of the wafer.

14. (Original) The sugar wafer according to claim 13, further comprising one or more of milk, cream, milk powder, whole egg, egg powder, soya flour, salt, lecithin, vanilla crystals, or a raising agent.

15. (Original) A confectionery product comprising the sugar wafer of claim 9 and a second confectionery material having a water activity below 0.5, wherein the second confectionery material is in direct contact with the sugar wafer.

16. (Original) A confectionery product comprising the sugar wafer of claim 11 and a second confectionery material having a water activity below 0.5, wherein the second confectionery material is in direct contact with the sugar wafer.

17. (Original) A confectionery product comprising the sugar wafer of claim 13 and a second confectionery material having a water activity below 0.5, wherein the second confectionery material is in direct contact with the sugar wafer.

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18. (Original) A confectionery product comprising the sugar wafer of claim 9, a second confectionery material, and a moisture barrier between the sugar wafer and the second confectionery material.

19. (Original) A confectionery product comprising the sugar wafer of claim 11, a second confectionery material, and a moisture barrier between the sugar wafer and the second confectionery material.

20. (Original) A confectionery product comprising the sugar wafer of claim 13, a second confectionery material, and a moisture barrier between the sugar wafer and the second confectionery material.